

11-24-00

Packet No. 4704/USA/ETCH/SILICON

JC849 U.S. PTO
11/21/00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

JC914 U.S. PTO
09/7/18319
11/21/00

Patent Application
Commissioner for Patents
Washington, D.C. 20231

Re: Inventor(s): Yuen, et al
Title: Etching a Substrate in a Process Zone

Transmitted herewith is the patent application identified above, including:

☒ Specification, claims and abstract, totaling 34 pages.

Drawings totaling 6 pages, X Formal Informal.

Executed Declaration and Power of Attorney.

Information Disclosure Statement, PTO-1449 form, and copies of citations

Assignment of the invention to Applied Materials, Inc. and Assignment Recordation Cover Sheet

Post Card for return

FEE CALCULATION					
Fee Items	Claims Filed	Included with Basic Fee	Extra Claims	Fee Rate	Total
1 Claims	54	- 20 =	34	x 18.00	\$612.00
pendent Claims	8	- 3 =	5	x 80.00	\$400.00
c Filing Fee				710.00	\$710.00
TOTAL FEES					\$1,722.00

☒ The Commissioner is hereby authorized to charge \$1722.00 to Deposit Account No. 50-1074.

☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 50-1074. A duplicate copy of this transmittal is enclosed.

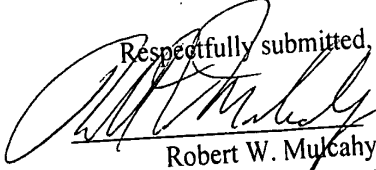
☒ Please address all future correspondence to:
APPLIED MATERIALS, INC.
Patent Department
P.O. Box 450A
Santa Clara, CA 95052

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to:

Box Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

Express Mail Receipt No. EL35691580245 Date of Deposit 11-21-2000

By Robert W. Mulcahy Signature Robert W. Mulcahy

Respectfully submitted,

Robert W. Mulcahy
Registration No. 25,436